

bottom outline and a plurality of load-bearing mounting feet disposed along the equipment's bottom outline comprising:

a plurality of support legs; and

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a frame disposed on the plurality of support legs, the frame having a frame outline which substantially duplicates the bottom outline of the semiconductor processing equipment, the frame being configured to support the installation of semiconductor processing equipment.

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21. (Amended) Support apparatus for an installation of semiconductor processing equipment having a plurality of load-bearing mounting feet at a bottom of the semiconductor processing equipment comprising:

a plurality of support legs; and

a frame disposed on the plurality of support legs, the frame being configured to support the installation of semiconductor processing equipment and to provide one or more facilities connection locations that are pre-aligned to one or more facilities connection points of the semiconductor processing equipment.

Please add new claims 23-26 as follows:

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23. (New) The support apparatus of claim 1 wherein the plurality of support legs include at least one support leg aligned to each one of the plurality of load-bearing mounting feet.

24. (New) The support apparatus of claim 21 wherein the plurality of support legs include at least one support leg aligned to each one of the plurality of load-bearing mounting feet.